

SOT908-2

plastic thermal enhanced very thin small outline package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON8
Package type industry code	HVSON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-229
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	8-3-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	8	-	

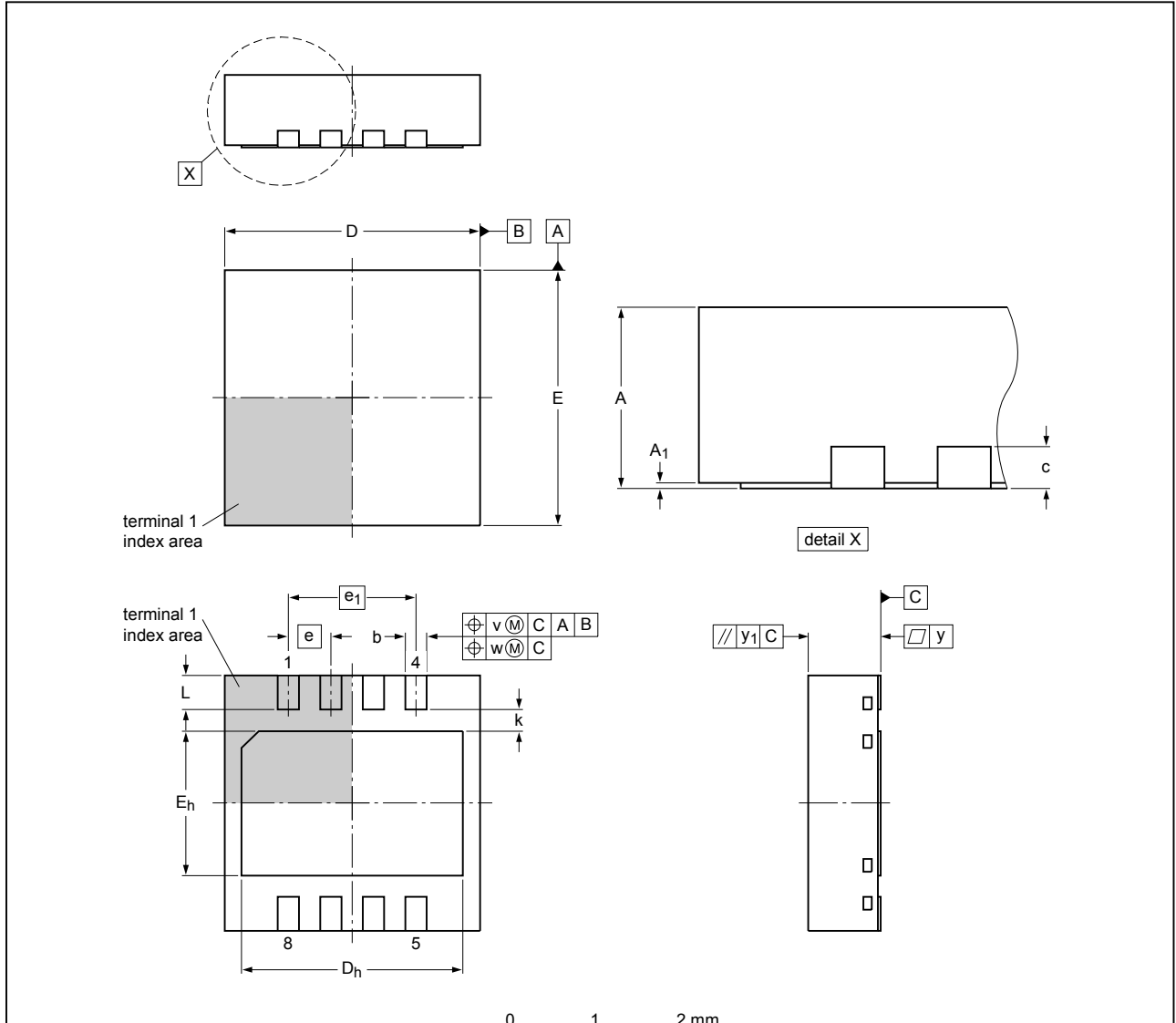


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2. Package outline

HVSON8: plastic, thermal enhanced very thin small outline package; no leads; 8 terminals; body 3 x 3 x 0.85 mm

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Dimensions

Unit ⁽¹⁾	A	A ₁	b	c	D	D _h	E	E _h	e	e ₁	k	L	v	w	y	y ₁
max	1.00	0.05	0.30		3.1	2.65	3.1	1.75			0.30	0.45				
mm nom	0.85	0.03	0.25	0.2	3.0	2.60	3.0	1.70	0.5	1.5	0.25	0.40	0.1	0.05	0.05	0.1
min	0.80	0.00	0.20		2.9	2.55	2.9	1.65			0.20	0.35				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot908-2_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT908-2	---	MO-229	---		10-02-17 10-03-08

Fig. 1. Package outline HVSON8 (SOT908-2)

3. Legal information

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